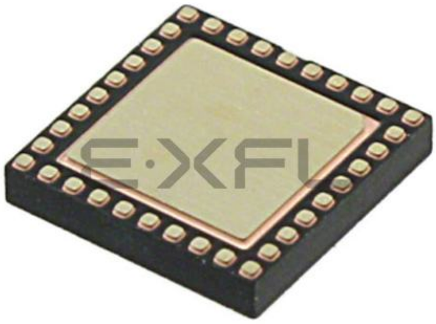

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-VFTLA Exposed Pad
Supplier Device Package	36-VTLA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep64mc203t-i-tl

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

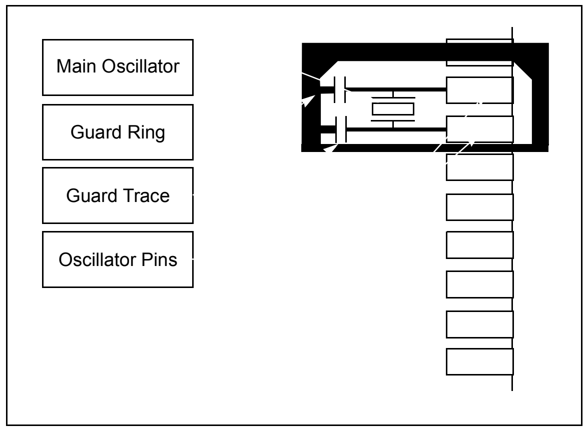
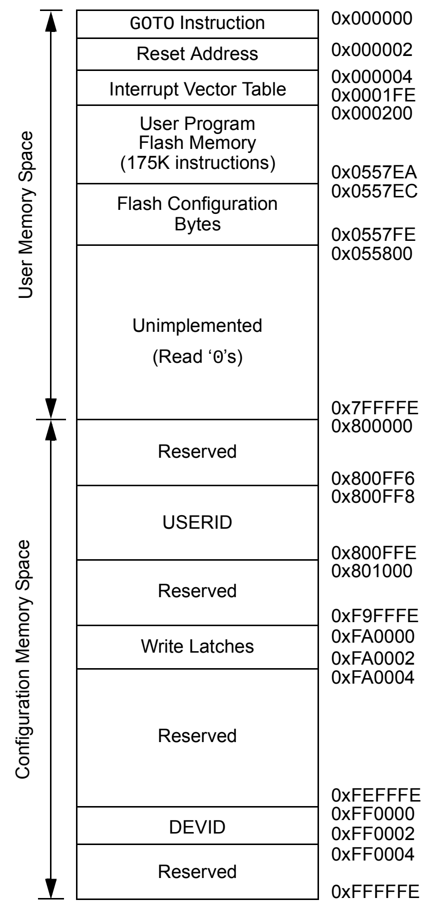


FIGURE 4-5: PROGRAM MEMORY MAP FOR dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X AND PIC24EP512GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-31: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	06A0	—	INT1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>							0000
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>							0000
RPINR7	06AE	—	IC2R<6:0>							—	IC1R<6:0>							0000
RPINR8	06B0	—	IC4R<6:0>							—	IC3R<6:0>							0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>							0000
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>							0000
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>							0000
RPINR22	06CC	—	SCK2INR<6:0>							—	SDI2R<6:0>							0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>							0000
RPINR26	06D4	—	—	—	—	—	—	—	—	—	C1RXR<6:0>							0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-32: PERIPHERAL PIN SELECT INPUT REGISTER MAP FOR dsPIC33EPXXXMC50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	06A0	—	INT1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR1	06A2	—	—	—	—	—	—	—	—	—	INT2R<6:0>							0000
RPINR3	06A6	—	—	—	—	—	—	—	—	—	T2CKR<6:0>							0000
RPINR7	06AE	—	IC2R<6:0>							—	IC1R<6:0>							0000
RPINR8	06B0	—	IC4R<6:0>							—	IC3R<6:0>							0000
RPINR11	06B6	—	—	—	—	—	—	—	—	—	OCFAR<6:0>							0000
RPINR12	06B8	—	FLT2R<6:0>							—	FLT1R<6:0>							0000
RPINR14	06BC	—	QEB1R<6:0>							—	QEA1R<6:0>							0000
RPINR15	06BE	—	HOME1R<6:0>							—	INDX1R<6:0>							0000
RPINR18	06C4	—	—	—	—	—	—	—	—	—	U1RXR<6:0>							0000
RPINR19	06C6	—	—	—	—	—	—	—	—	—	U2RXR<6:0>							0000
RPINR22	06CC	—	SCK2INR<6:0>							—	SDI2R<6:0>							0000
RPINR23	06CE	—	—	—	—	—	—	—	—	—	SS2R<6:0>							0000
RPINR26	06D4	—	—	—	—	—	—	—	—	—	C1RXR<6:0>							0000
RPINR37	06EA	—	SYNCI1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR38	06EC	—	DTCMP1R<6:0>							—	—	—	—	—	—	—	—	0000
RPINR39	06EE	—	DTCMP3R<6:0>							—	DTCMP2R<6:0>							0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR(1)	OVBERR(1)	COVAERR(1)	COVBERR(1)	OVATE(1)	OVBTE(1)	COVTE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR(1)	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit(1)
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit(1)
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit(1)
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit(1)
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit(1)
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **DMACERR:** DMAC Trap Flag bit
1 = DMAC trap has occurred
0 = DMAC trap has not occurred

Note 1: These bits are available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

21.0 ENHANCED CAN (ECAN™) MODULE (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

21.1 Overview

The Enhanced Controller Area Network (ECAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The dsPIC33EPXXXGP/MC50X devices contain one ECAN module.

The ECAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH CAN specification. The module supports CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader can refer to the BOSCH CAN specification for further details.

The ECAN module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to eight transmit buffers with application specified prioritization and abort capability (each buffer can contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer can contain up to 8 bytes of data)
- Up to 16 full (Standard/Extended Identifier) acceptance filters
- Three full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to Input Capture (IC2) module for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bits
11 = Reserved
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bits (same values as bits<15:14>)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bits (same values as bits<15:14>)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bits (same values as bits<15:14>)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bits (same values as bits<15:14>)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bits (same values as bits<15:14>)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bits (same values as bits<15:14>)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bits (same values as bits<15:14>)

REGISTER 21-26: CxTRmnCON: ECANx TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm[(1)]	TXLARBm[(1)]	TXERRm[(1)]	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 See Definition for bits<7:0>, Controls Buffer n

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer

bit 6 **TXABTm:** Message Aborted bit[(1)]
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit[(1)]
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit[(1)]
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to ‘0’ while set requests a message abort

bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

Note: The buffers, SID, EID, DLC, Data Field, and Receive Status registers are located in DMA RAM.

BUFFER 21-5: ECAN™ MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 3<15:8>:** ECAN Message Byte 3 bits

bit 7-0 **Byte 2<7:0>:** ECAN Message Byte 2 bits

BUFFER 21-6: ECAN™ MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 5<15:8>:** ECAN Message Byte 5 bits

bit 7-0 **Byte 4<7:0>:** ECAN Message Byte 4 bits

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1	**BUFM:** Buffer Fill Mode Select bit 1 = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt 0 = Always starts filling the buffer from the start address.
bit 0	**ALTS:** Alternate Input Sample Mode Select bit 1 = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample 0 = Always uses channel input selects for Sample MUXA

REGISTER 23-7: AD1CSSH: ADC1 INPUT SCAN SELECT REGISTER HIGH(1)

R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	—	—	—	CSS26(2)	CSS25(2)	CSS24(2)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADC1 Input Scan Selection bit
1 = Selects CTMU capacitive and time measurement for input scan (Open)
0 = Skips CTMU capacitive and time measurement for input scan (Open)

bit 14 **CSS30:** ADC1 Input Scan Selection bit
1 = Selects CTMU on-chip temperature measurement for input scan (CTMU TEMP)
0 = Skips CTMU on-chip temperature measurement for input scan (CTMU TEMP)

bit 13-11 **Unimplemented:** Read as ‘0’

bit 10 **CSS26:** ADC1 Input Scan Selection bit(2)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADC1 Input Scan Selection bit(2)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADC1 Input Scan Selection bit(2)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: All AD1CSSH bits can be selected by user software. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

TABLE 24-1: PTG STEP COMMAND FORMAT (CONTINUED)

bit 3-0	Step Command	OPTION<3:0>	Option Description
	PTGCTRL[(1)]	0000	Reserved.
		0001	Reserved.
		0010	Disable Step Delay Timer (PTGSD).
		0011	Reserved.
		0100	Reserved.
		0101	Reserved.
		0110	Enable Step Delay Timer (PTGSD).
		0111	Reserved.
		1000	Start and wait for the PTG Timer0 to match the Timer0 Limit Register.
		1001	Start and wait for the PTG Timer1 to match the Timer1 Limit Register.
		1010	Reserved.
		1011	Wait for the software trigger bit transition from low-to-high before continuing (PTGSWT = 0 to 1).
		1100	Copy contents of the Counter 0 register to the AD1CHS0 register.
		1101	Copy contents of the Counter 1 register to the AD1CHS0 register.
		1110	Copy contents of the Literal 0 register to the AD1CHS0 register.
		1111	Generate triggers indicated in the Broadcast Trigger Enable register (PTGBTE).
	PTGADD[(1)]	0000	Add contents of the PTGADJ register to the Counter 0 Limit register (PTGC0LIM).
		0001	Add contents of the PTGADJ register to the Counter 1 Limit register (PTGC1LIM).
		0010	Add contents of the PTGADJ register to the Timer0 Limit register (PTGT0LIM).
		0011	Add contents of the PTGADJ register to the Timer1 Limit register (PTGT1LIM).
		0100	Add contents of the PTGADJ register to the Step Delay Limit register (PTGSDLIM).
		0101	Add contents of the PTGADJ register to the Literal 0 register (PTGL0).
		0110	Reserved.
		0111	Reserved.
	PTGCOPY[(1)]	1000	Copy contents of the PTGHOLD register to the Counter 0 Limit register (PTGC0LIM).
		1001	Copy contents of the PTGHOLD register to the Counter 1 Limit register (PTGC1LIM).
		1010	Copy contents of the PTGHOLD register to the Timer0 Limit register (PTGT0LIM).
		1011	Copy contents of the PTGHOLD register to the Timer1 Limit register (PTGT1LIM).
		1100	Copy contents of the PTGHOLD register to the Step Delay Limit register (PTGSDLIM).
		1101	Copy contents of the PTGHOLD register to the Literal 0 register (PTGL0).
		1110	Reserved.
		1111	Reserved.

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a NOP instruction).

2: Refer to Table 24-2 for the trigger output descriptions.

3: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

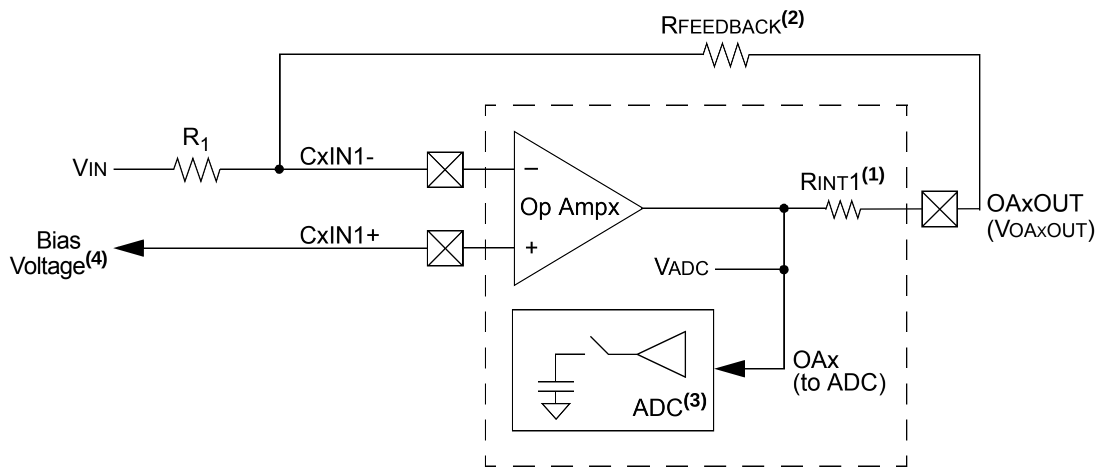
25.1 Op Amp Application Considerations

There are two configurations to take into consideration when designing with the op amp modules that are available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices. Configuration A (see Figure 25-6) takes advantage of the internal connection to the ADC module to route the output of the op amp directly to the ADC for measurement. Configuration B (see Figure 25-7) requires that the designer externally route the output of the op amp (OAxOUT) to a separate analog input pin (ANy) on the device. Table 30-55 in **Section 30.0 "Electrical Characteristics"** describes the performance characteristics for the op amps, distinguishing between the two configuration types where applicable.

25.1.1 OP AMP CONFIGURATION A

Figure 25-6 shows a typical inverting amplifier circuit taking advantage of the internal connections from the op amp output to the input of the ADC. The advantage of this configuration is that the user does not need to consume another analog input (ANy) on the device, and allows the user to simultaneously sample all three op amps with the ADC module, if needed. However, the presence of the internal resistance, RINT1, adds an error in the feedback path. Since RINT1 is an internal resistance, in relation to the op amp output (VOAXOUT) and ADC internal connection (VADC), RINT1 must be included in the numerator term of the transfer function. See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration. Figure 25-6 also defines the equations that should be used when calculating the expected voltages at points, VADC and VOAXOUT.

FIGURE 25-6: OP AMP CONFIGURATION A



$$V_{ADC} = \left(\frac{R_{FEEDBACK} + R_{INT1}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

Note 1: See Table 30-53 for the Typical value.
2: See Table 30-53 for the Minimum value for the feedback resistor.
3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).
4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

29.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

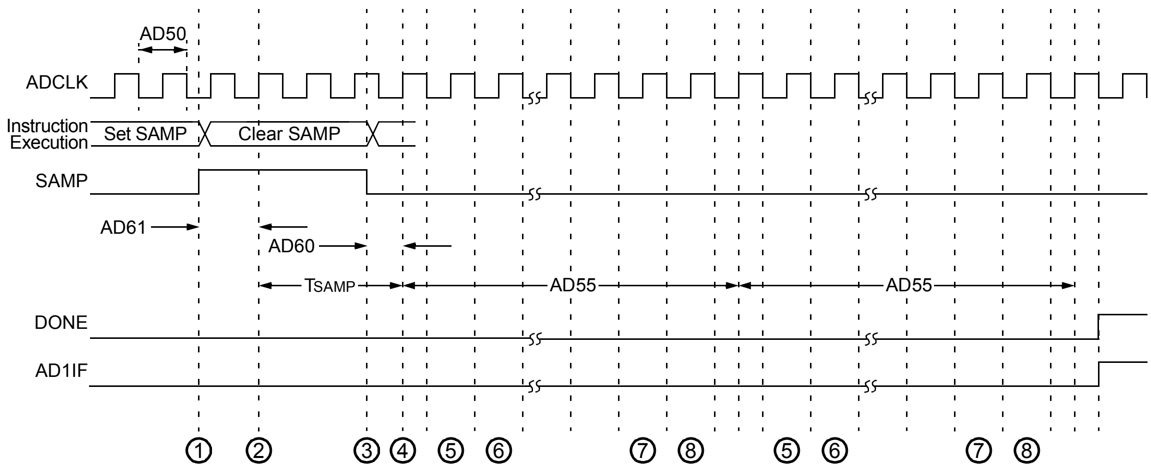
- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 30-39: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.
4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



① – Software sets AD1CON1. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **“Analog-to-Digital Converter (ADC)”** (DS70621) in the *“dsPIC33/PIC24 Family Reference Manual”*.

③ – Software clears AD1CON1. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

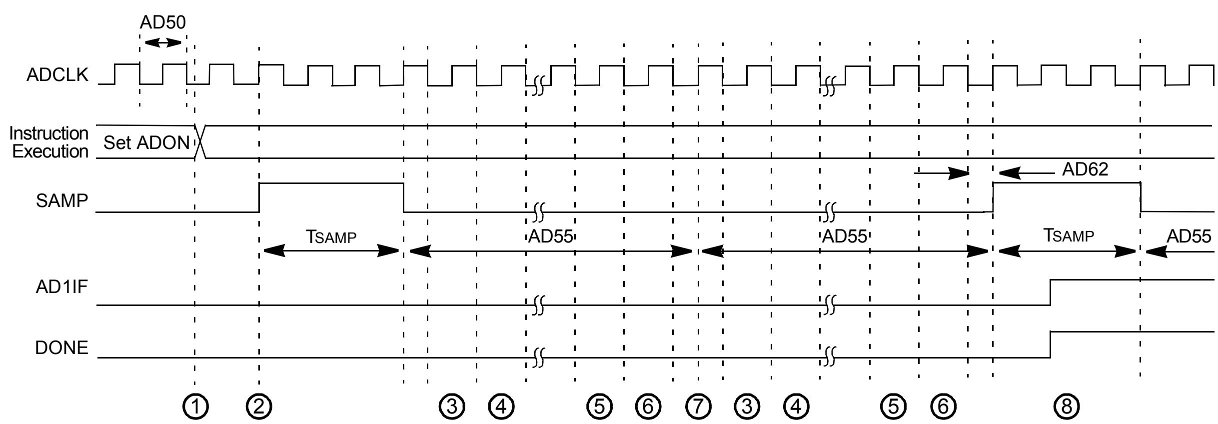
⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



① – Software sets AD1CON1. ADON to start AD operation.

② – Sampling starts after discharge period. TSAMP is described in **“Analog-to-Digital Converter (ADC)”** (DS70621) in the *“dsPIC33/PIC24 Family Reference Manual”*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC60e	1400	2500	μA	+150°C	3.3V	Base Power-Down Current **(Notes 1, 3)**
HDC61c	15	—	μA	+150°C	3.3V	Watchdog Timer Current: ΔIWDT **(Notes 2, 4)**

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC44e	12	30	mA	+150°C	3.3V	40 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC20	9	15	mA	+150°C	3.3V	10 MIPS
HDC22	16	25	mA	+150°C	3.3V	20 MIPS
HDC23	30	50	mA	+150°C	3.3V	40 MIPS

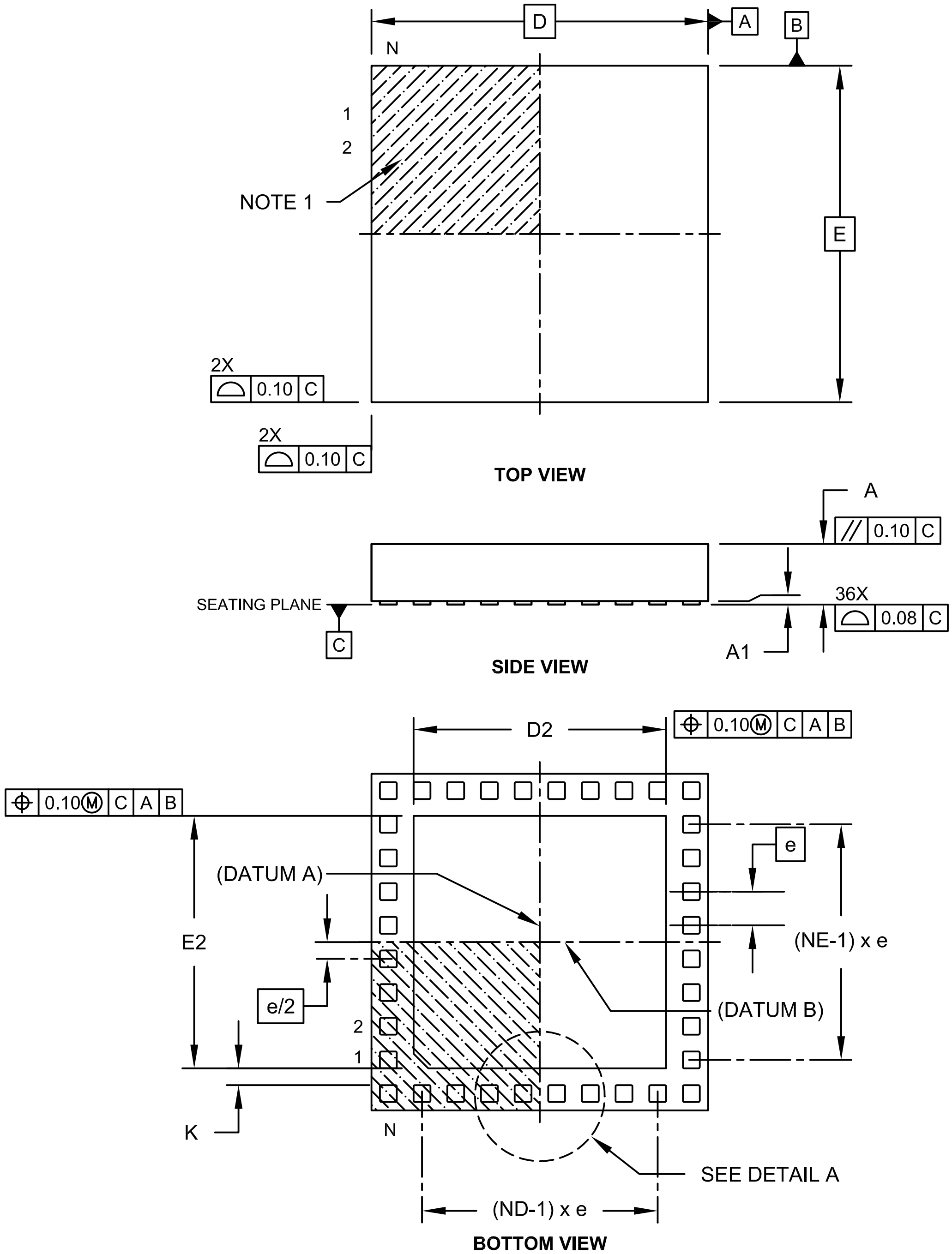
TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Parameter No.	**Typical**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	24	35	1:2	mA	+150°C	3.3V	40 MIPS
HDC72f(1)	14	—	1:64	mA			
HDC72g(1)	12	—	1:128	mA			

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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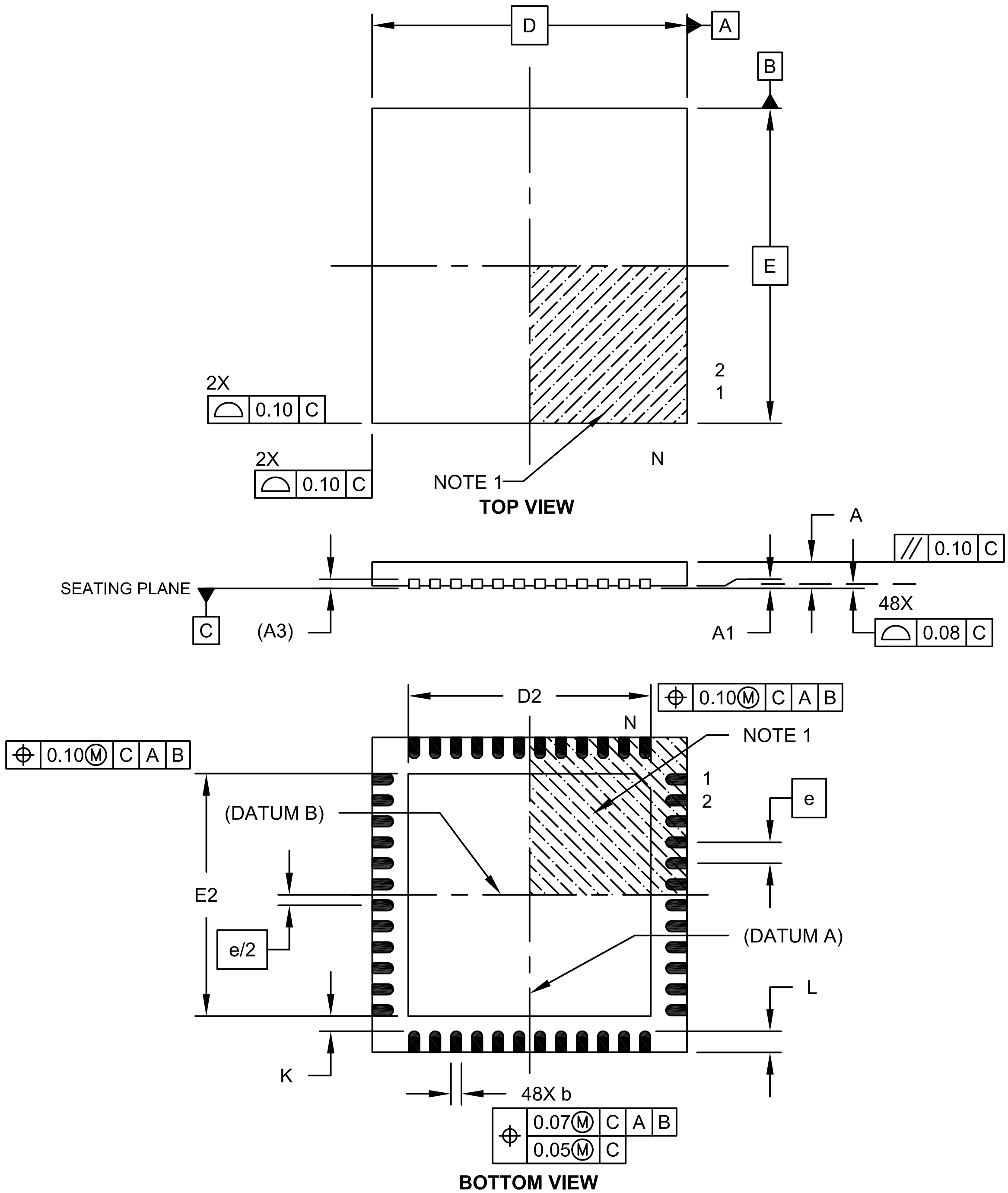
48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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